



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : ~~09/451,810~~ 09966222  
Applicant : Palmteer, et al.  
Filed : September 28, 2001  
Title : Improved Leadframe-based Chip Scale Package  
TC/A.U. : 2827  
Examiner : Cruz, Lourdes C.  
Docket No. : 17658  
(S&L No. P24,989A USA)

RECEIVED  
NOV - 3 2003  
TECHNOLOGY CENTER 2800

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Mail Stop AF, Commissioner for Patents, Box 1450, Alexandria, VA 22313-1450, on Monday, October 27, 2003.

*Dorothy M Musgreave*  
Dorothy M. Musgreave

RECEIVED  
DEC - 9 2003  
2600

AMENDMENT

Sir:

In response to the Final Office Action of August 27, 2003, please amend the above-identified Application as follows:

**Amendments to the Claims** are reflected in the "Listing of Claims," which begins on page 2 of this paper.

**Amendments to the Drawings** begin on page 6 and include both an attached replacement sheet and an annotated sheet showing changes.

**Remarks** begin on page 11 of this paper.

RECEIVED  
DEC - 1 2003  
TECHNOLOGY CENTER 2800